Time	Program	Speaker/Moderator
09:30	Registration General Assembly, Coffee	
10:00	General Assembly Swissphotonics	Christoph Harder / Christian Bosshard, Swissphotonics
10:30	Registration Workshop, Coffee	
11:00	Workshop: Photonics Integration & Packaging	
11:00	Welcome & Introduction	Christian Bosshard, Swissphotonics
11:05	The Swiss Photonics Integration Center	Christoph Harder, Swiss PIC
11:20	Session I: High-frequency	Christian Bosshard, Swissphotonics
11:20	Swiss high-speed PICs for data centers	Stefan Abel, Lumiphase
11:35	Packaging for ultra high-speed devices	Jürg Leuthold, ETH
11:50	Packaging the Future: Unlocking Photonics in Switzerland	Jérémy Borsenberger, Yotavis
12:05	Q&A	
12:20	Lunch / Labtour: Swiss PIC	Peter Moselund, Swiss PIC
13:20	Welcome	Landammann Dieter Egli and Robert Rudoph, CEO Park Innovaare
13:45	Panel: Packaging hub vs in-house packaging: How many packaging robots do we need?	Andreas Voelker, CSEM; John Jost, Enlightra; Tobias Lamprecht, OST; Andreas Hugi, Sensirion / Swiss PIC; Karlheinz Gulden, Coherent
14:30	Session II: Quantum photonics	Kirsten Moselund, PSI
14:30	Integrated photonics for scaling trapped ion quantum	Pavel Hrmo, ZuriQ
14:45	The packaging challenge in laser-based trapped-ion quantum computing	Cornelius Hempel, PSI
15:00	3D nano-printing is lighting the path toward scalable and reliable processes for seamlessly integrating active	Thorsten Mayer, Vanguard Automation
15:15	Q&A	
15:30	Coffee Break	
16:15	Session III: Discrete micro-optics	Christoph Harder, Swiss PIC
16:15	Towards mass production of reliable laser combs	Florian Emaury, Menhir Photonics
16:30	Micro-optical integration of SLED and LD light sources from the near-UV to the NIR	Marcus Duelk, Exalos / indie
16:45	Shaping Light for XR devices: Photonic and Optics Integration Challenges and Opportunities	Markus Rossi, AlphaLum
17:00	Q&A	
17:15	Networking Apero	
19:00	Close	